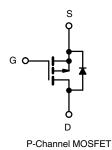


## P-Channel 60 V (D-S) 175 °C MOSFET

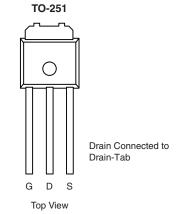
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	- 60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.0135			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.017			
I <sub>D</sub> (A)	- 50			
Configuration	Single			



#### **FEATURES**

- Trench Power MOSFET
- Package with Low Thermal Resistance
- 100 % R<sub>g</sub> and UIS Tested





<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	- 60	· ·	
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuous Drain Current <sup>a</sup>	T <sub>C</sub> = 25 °C	1	- 50		
	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	- 38		
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	- 50	Α	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	- 200		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	- 52		
Single Pulse Avalanche Energy	L=0.1 MH	E <sub>AS</sub>	135	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	136	W	
	T <sub>C</sub> = 125 °C	ГD	45		
Operating Junction and Storage Temperature Range	Э	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount <sup>c</sup>	$R_{thJA}$	50	°C/W	
Junction-to-Case (Drain)		$R_{thJC}$	1.1	C/VV	

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq 300~\mu s,\,duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).



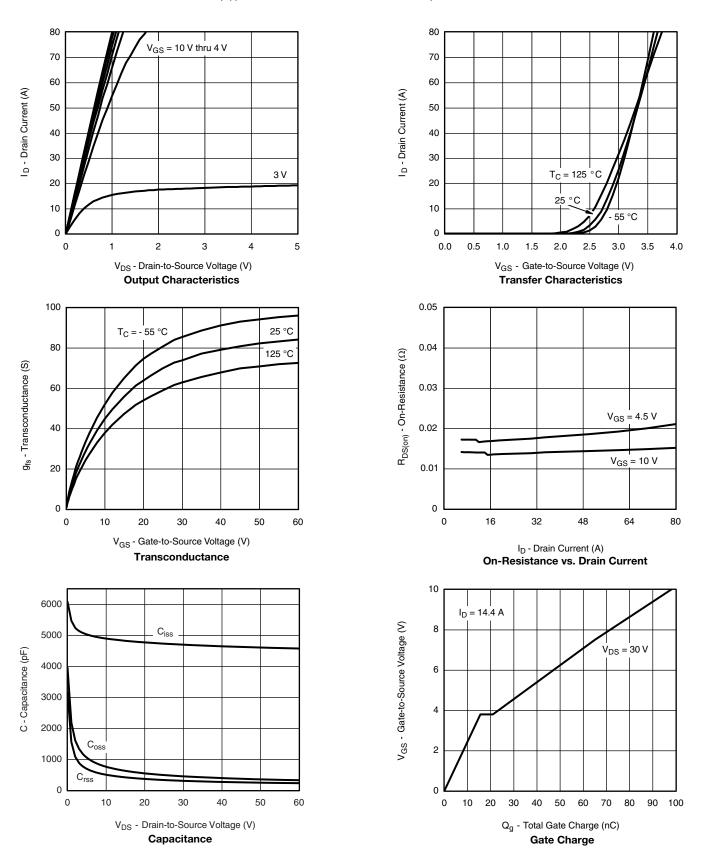
SPECIFICATIONS (T <sub>C</sub> = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		- 60	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	- 1.5	-	- 2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = - 60 V	-	-	- 1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = - 60 V, T <sub>J</sub> = 125 °C		-	- 50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = - 60 V, T <sub>J</sub> = 175 °C	-	-	- 150	1
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = - 10 V	V <sub>DS</sub> ≥ - 5 V	- 50	-	-	Α
		V <sub>GS</sub> = - 10 V	I <sub>D</sub> = - 17 A	-	0.0135	-	Ω
Dunin Course On Otata Basistanas		V <sub>GS</sub> = - 10 V	I <sub>D</sub> = - 50 A, T <sub>J</sub> = 125 °C	-	0.026	-	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V	I <sub>D</sub> = - 50 A, T <sub>J</sub> = 175 °C	_	0.032	-	
		V <sub>GS</sub> = - 4.5 V	I <sub>D</sub> = - 14 A	_	0.017	-	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> =	- 15 V, I <sub>D</sub> = - 17 A	-	50	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		= 0 V V <sub>DS</sub> = - 25 V, f = 1 MHz	=.	4730	5910	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$			485	606	
Reverse Transfer Capacitance	C <sub>rss</sub>	1		-	330	410	
Total Gate Charge <sup>c</sup>	Qg			-	98	150	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = - 10 V	$V_{DS} = -30 \text{ V}, I_{D} = -50 \text{ A}$	-	15	23	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>	1		-	21	32	
Gate Resistance	Rg	f = 1 MHz		1.47	2.9	4.42	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	15	18	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -30 \text{ V}, R_L = 0.6 \Omega$ $I_D \cong -50 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 6.0 \Omega$		-	12	16	- ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	112	125	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	39	48	1
Source-Drain Diode Ratings and Characteristics <sup>b</sup>							
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	- 200	Α
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = - 50 A, V <sub>GS</sub> = 0 V		-	- 0.8	- 1.5	V

#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

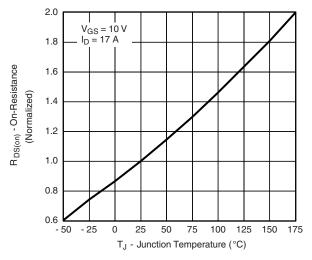


## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

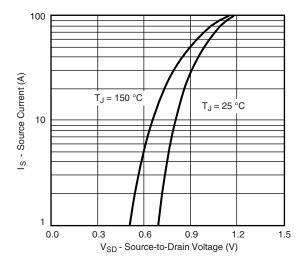




## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

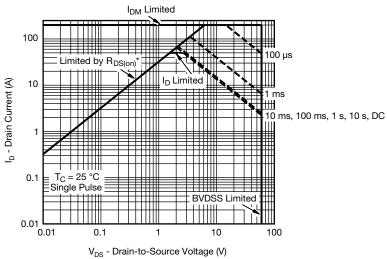






**Source Drain Diode Forward Voltage** 

## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)

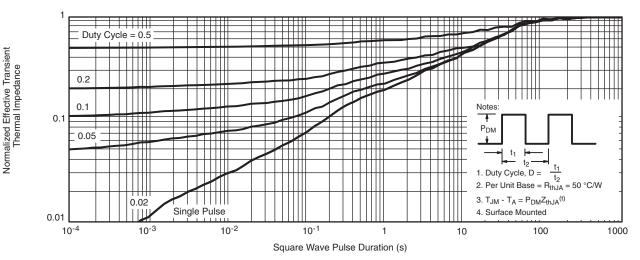


\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

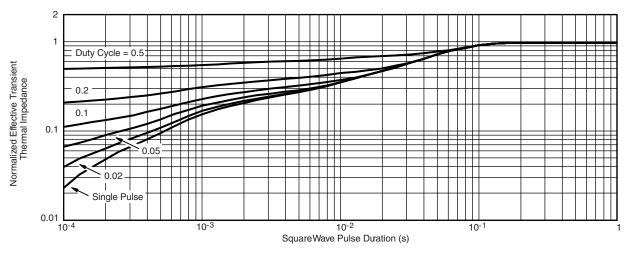
**Safe Operating Area** 



## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

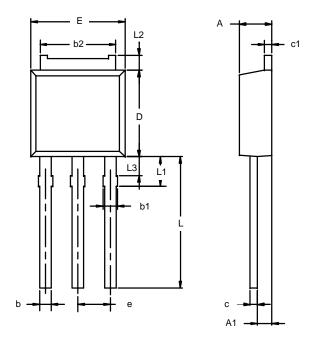
#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction to Case (25°C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



### **TO-251AA**



Note: Dimension L3 is for reference only	y.
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	MILLIM	IETERS	INC	HES
Dim	Min	Max	Min	Max
Α	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
С	0.46	0.58	0.018	0.023
с1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
Е	6.48	6.73	0.255	0.265
е	2.28 BSC		0.090	BSC
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060



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